

LDC Reference Coils User's Guide

User's Guide



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LDC Reference Coils User's Guide

1 Overview

The Texas Instruments LDC (inductance-to-digital converter) reference coil board is a collection of sensors that can be used with any LDC evaluation module. The reference coils can replace the default EVM sensor for applications in which the default sensor is not suitable. The sensor options on the reference coil board include different coil geometries which may be more suitable for specific applications. The board contains three different types of coil geometries: circular, rectangular, and stretched. Circular and rectangular coils are typically used in the applications requiring distance sensing or for lateral position sensing with triangular targets. Stretched coils provide an asymmetric field and are typically used for lateral sensing with rectangular targets.

To avoid interference between neighboring coils, it is necessary to separate the coils along the perforations before usage.

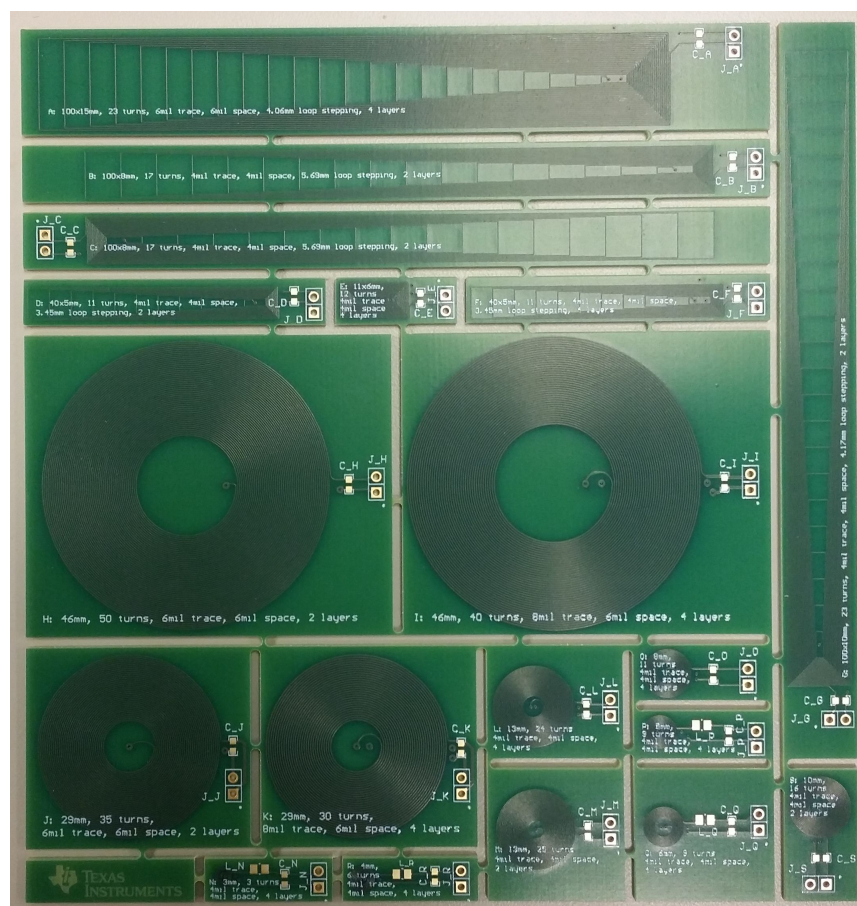


Figure 1. LDC Reference Coils Board (Top View)

Sensor capacitors are not populated by default. Before using the coils, it is necessary to solder a sensor capacitor onto the appropriate 0603 footprint. Once the oscillation frequency and the coil sensor are selected, the appropriate capacitor value should be chosen according to the following formula:

$$f_0 = \frac{1}{2\pi\sqrt{LC}}$$

Coils N, P, Q, and R (see [Table 1](#)) have an additional 0805 size footprint to add a series inductor. Adding a series inductor allows operation of the sensor within the R_P and f_{SENSOR} boundary conditions of the LDC (refer to [E2E Inductive Sensing](#)).

For further information on LDC sensors and sensor frequency constraints, refer to [LDC Sensor Design](#).

2 Coil Characteristics

The table below describes geometries of each coil.

Table 1. Coil Characteristics Summary

Coil	Type	Dimensions	Turns / Layer	Trace Width	Trace Spacing	Stepping	Layers
		(mm)		(mm)	(mm)	(mm)	
A	Stretched	100 * 15	23	0.15 (6 mil)	0.15 (6 mil)	4.06	4
B	Stretched (differential)	100 * 8	17	0.10 (4 mil)	0.10 (4 mil)	5.69	2
C	Stretched (differential)	100 * 8	17	0.10 (4 mil)	0.10 (4 mil)	5.69	2
D	Stretched	40 * 5	11	0.10 (4 mil)	0.10 (4 mil)	3.45	2
E	Rectangular	11 * 6	12	0.10 (4 mil)	0.10 (4 mil)	-	4
F	Stretched	40 * 5	11	0.10 (4 mil)	0.10 (4 mil)	3.45	4
G	Stretched	100 * 10	23	0.10 (4 mil)	0.10 (4 mil)	4.17	2
H	Circular	∅ = 46	50	0.15 (6 mil)	0.15 (6 mil)	-	2
I	Circular	∅ = 46	40	0.20 (8 mil)	0.15 (6 mil)	-	4
J	Circular	∅ = 29	35	0.15 (6 mil)	0.15 (6 mil)	-	2
K	Circular	∅ = 29	30	0.20 (8 mil)	0.15 (6 mil)	-	4
L	Circular	∅ = 13	24	0.10 (4 mil)	0.10 (4 mil)	-	4
M	Circular	∅ = 13	25	0.10 (4 mil)	0.10 (4 mil)	-	2
N	Circular	∅ = 3	3	0.10 (4 mil)	0.10 (4 mil)	-	4
O	Circular	∅ = 8	11	0.10 (4 mil)	0.10 (4 mil)	-	4
P	Circular	∅ = 5	9	0.10 (4 mil)	0.10 (4 mil)	-	4
Q	Circular	∅ = 6	9	0.10 (4 mil)	0.10 (4 mil)	-	4
R	Circular	∅ = 4	6	0.10 (4 mil)	0.10 (4 mil)	-	4
S	Circular	∅ = 10	16	0.10 (4 mil)	0.10 (4 mil)	-	2

3 Coil Characterization Data

The following graphs show L, R_S , and Q vs. frequency, as well as the self-resonant frequency of the coil. All measurements have been taken without a sensor capacitor, using an HP 4194A Impedance/Gain-Phase analyzer .

Coil A: 100x15mm, 23 turns, 6mil trace, 6mil spacing, 4.06mm loop stepping, 4 layers

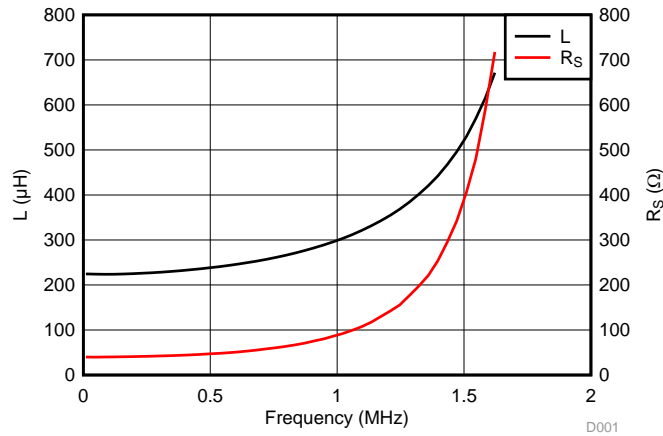


Figure 2. Coil A: L, R_s vs. Frequency

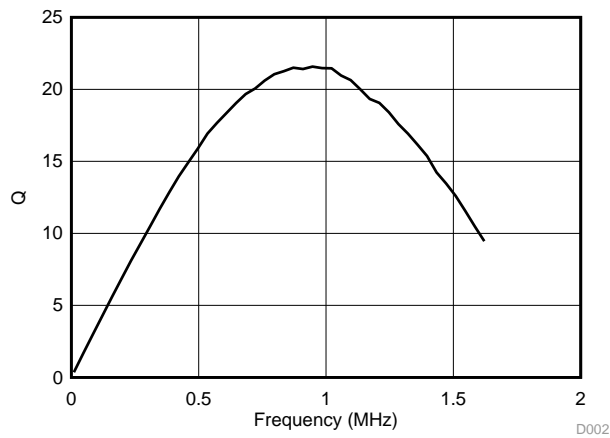
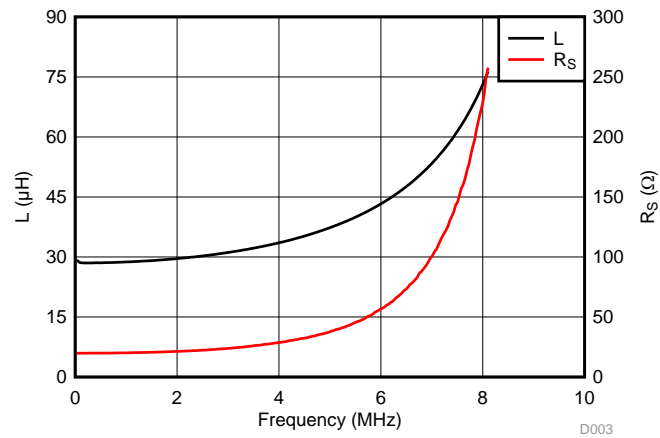
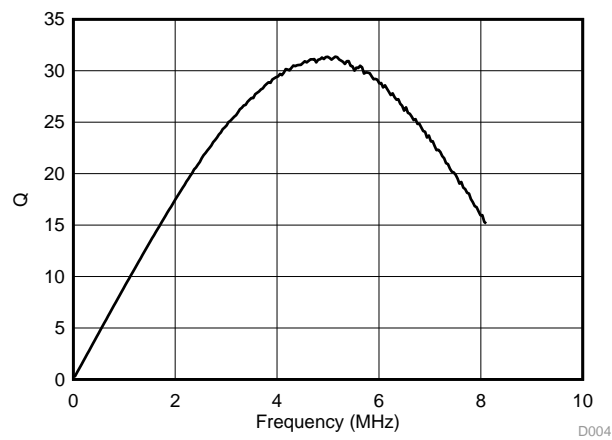


Figure 3. Coil A: Q vs. Frequency

Self-resonant frequency (SRF): 1.9MHz

Coil B, C: 100x8mm, 17 turns, 4mil trace, 4mil spacing, 5.69mm loop stepping, 2 layers

Figure 4. Coil B: L, R_s vs. Frequency

Figure 5. Coil B: Q vs. Frequency

Self-resonant frequency (SRF): 10.0MHz

Note that coils B and C are identical and can be used for differential lateral design evaluation

Coil D: 40x5mm, 11 turns, 4mil trace, 4mil spacing, 3.45mm loop stepping, 2 layers

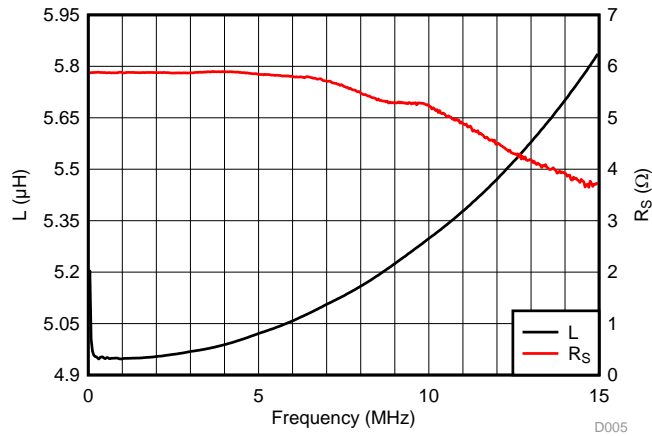


Figure 6. Coil D: L, R_s vs. Frequency

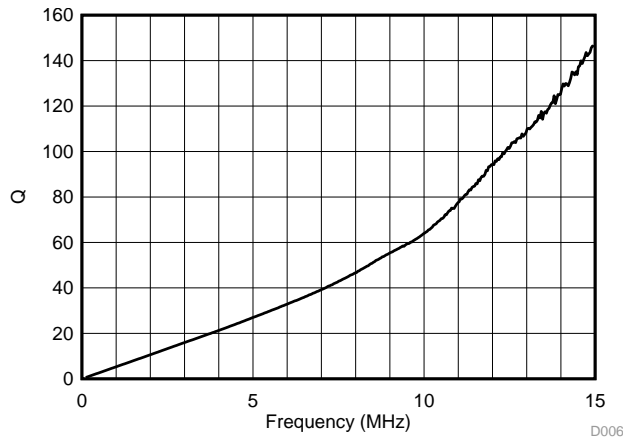


Figure 7. Coil D: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil E: 11x6mm, 12 turns, 4 mil trace, 4 layers

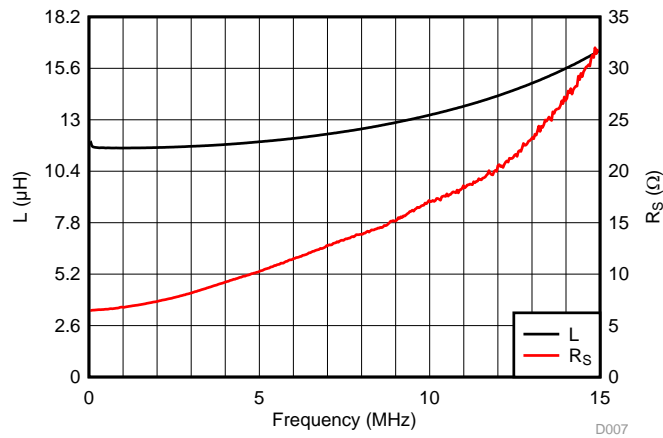


Figure 8. Coil E: L, R_s vs. Frequency

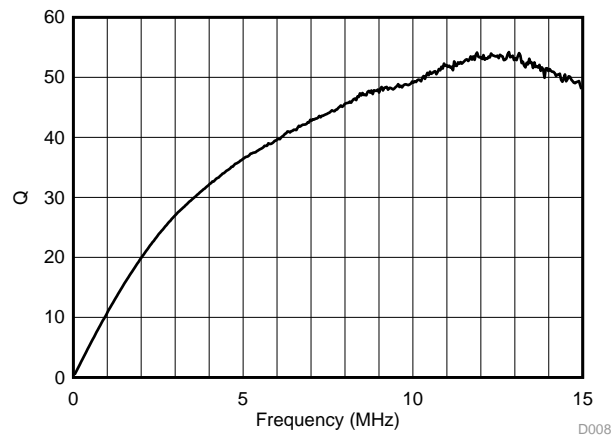


Figure 9. Coil E: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil F: 40x5mm, 11 turns, 4mil trace, 4mil spacing, 3.45mm loop stepping, 4 layers

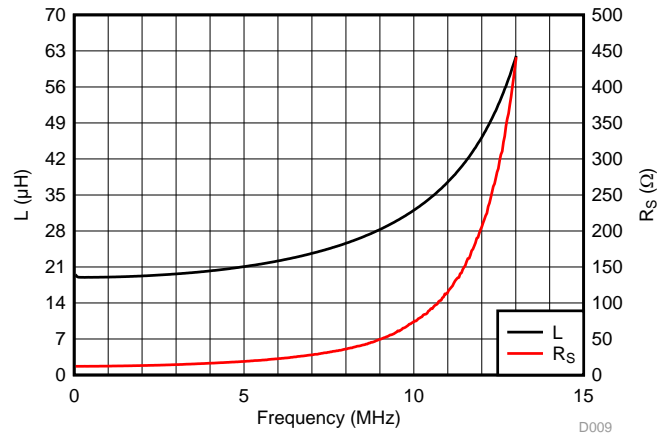


Figure 10. Coil F: L, R_s vs. Frequency

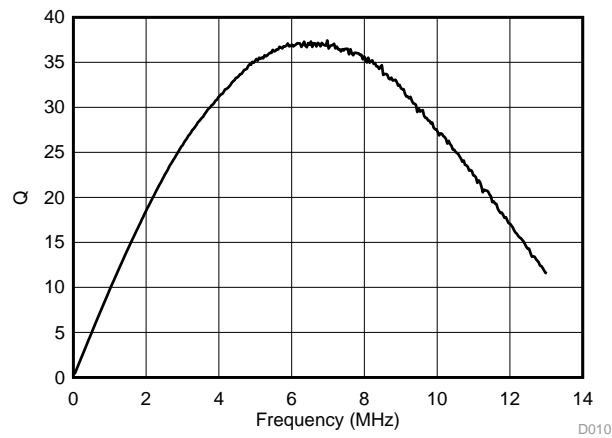


Figure 11. Coil F: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil G: 100x10mm, 23 turns, 4mil trace, 4mil spacing, 4.17mm loop stepping, 2 layers

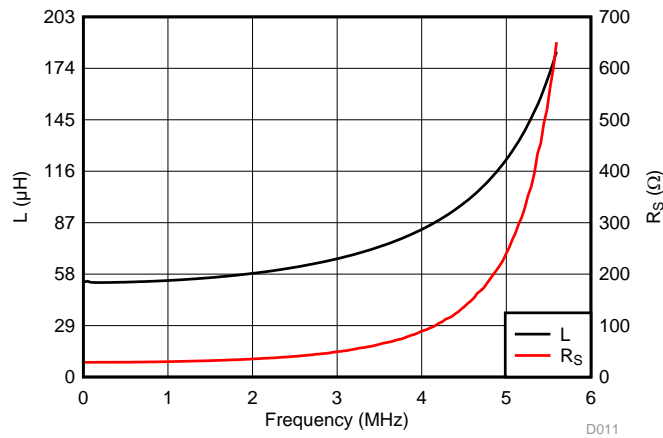


Figure 12. Coil G: L, R_s vs. Frequency

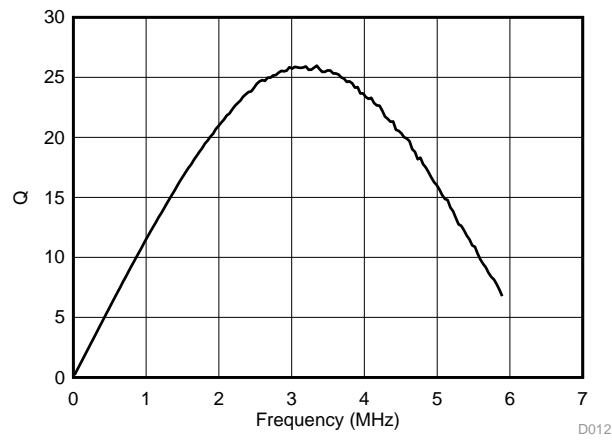


Figure 13. Q vs. Frequency

Self-resonant frequency (SRF): 6.5MHz

Coil H: 46mm, 50 turns, 6mil trace, 6mil spacing, 2 layers

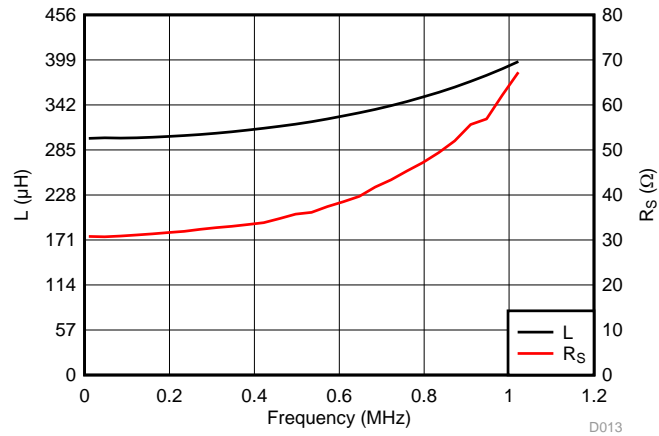


Figure 14. Coil H: L, R_s vs. Frequency

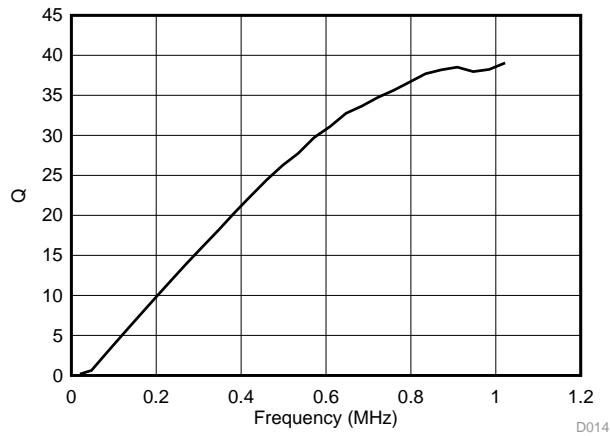


Figure 15. Coil H: Q vs. Frequency

Self-resonant frequency (SRF): 2.0MHz

Coil I: 46mm, 40 turns, 8mil trace, 6mil spacing, 4 layers

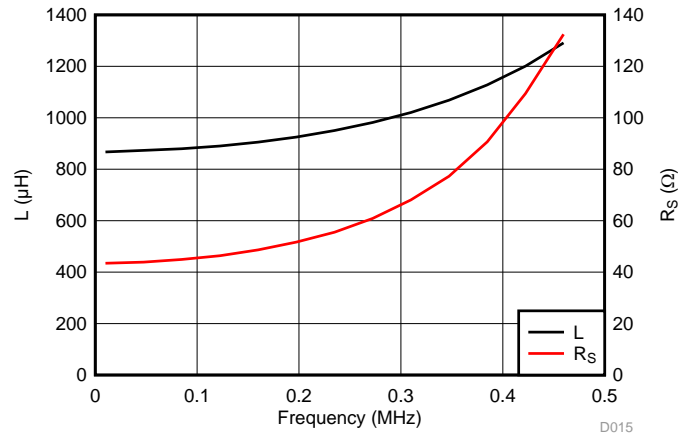


Figure 16. Coil I: L, R_s vs. Frequency

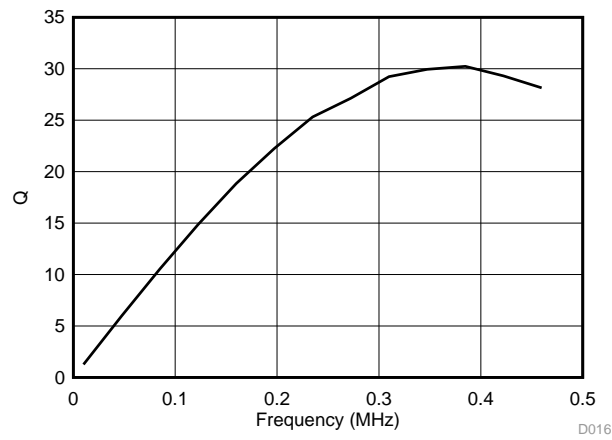


Figure 17. Coil I: Q vs. Frequency

Self-resonant frequency (SRF): 0.8MHz

Coil J: 29mm, 35 turns, 6mil trace, 6mil spacing, 2 layers

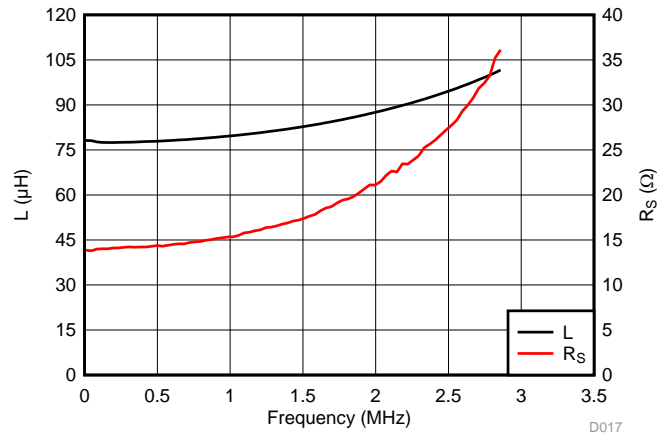


Figure 18. Coil J: L, R_s vs. Frequency

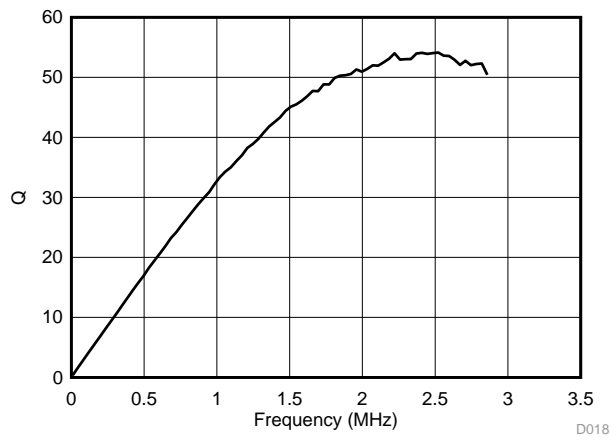


Figure 19. Coil J: Q vs. Frequency

Self-resonant frequency (SRF): 5.7MHz

Coil K: 29mm, 30 turns, 8mil trace, 6mil spacing, 4 layers

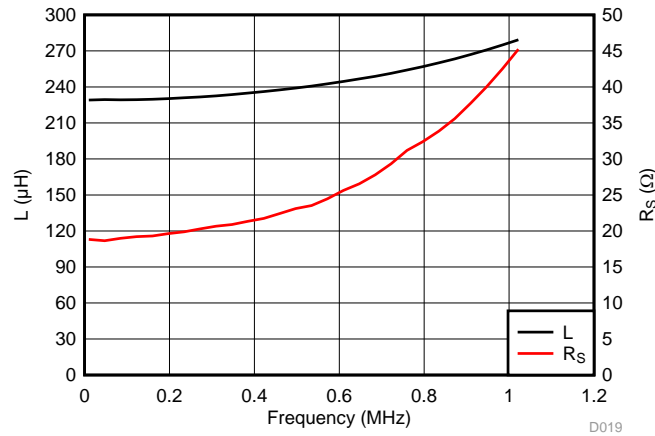


Figure 20. Coil K: L, R_s vs. Frequency

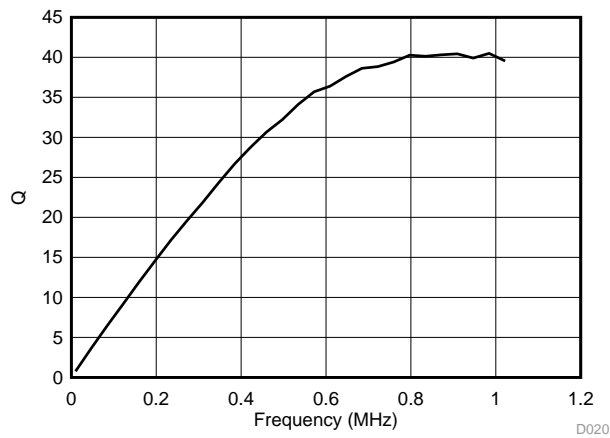


Figure 21. Coil K: Q vs. Frequency

Self-resonant frequency (SRF): 2.3MHz

Coil L: 13mm, 24 turns, 4mil trace, 4mil spacing, 4 layers

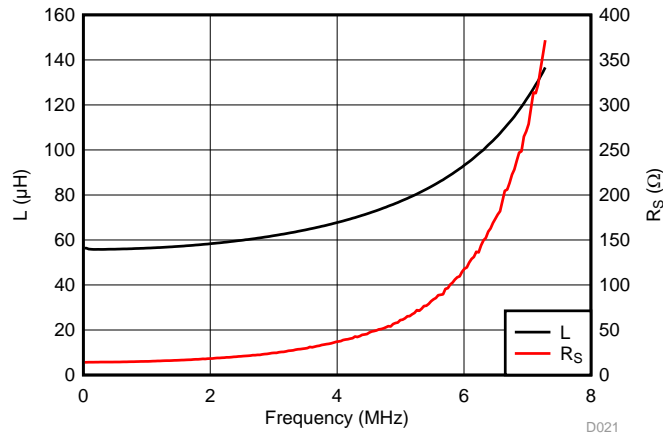


Figure 22. Coil L: L, R_s vs. Frequency

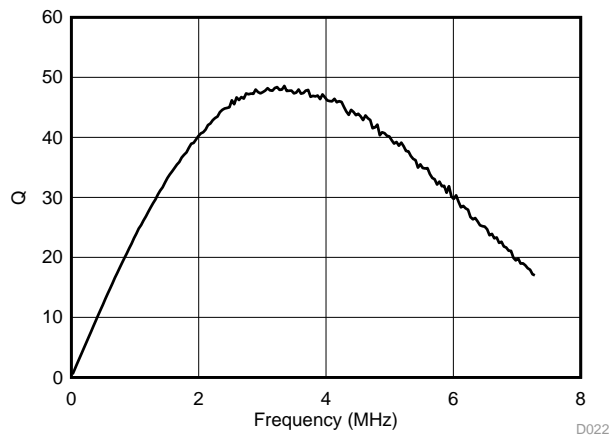


Figure 23. Coil L: Q vs. Frequency

Self-resonant frequency (SRF): 9.3MHz

Coil M: 13mm, 25 turns, 4mil trace, 4mil spacing, 2 layers

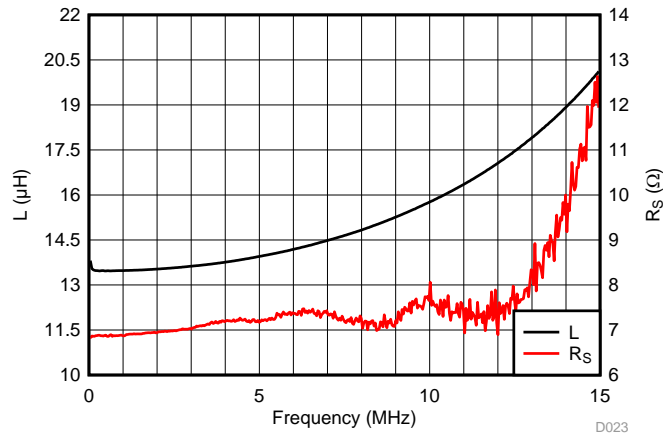


Figure 24. Coil M: L, R_s vs. Frequency

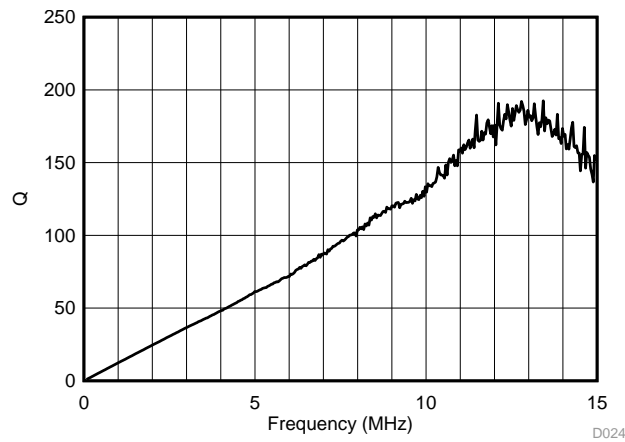


Figure 25. Coil M: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil N: 3mm, 3 turns, 4mil trace, 4mil spacing, 4 layers

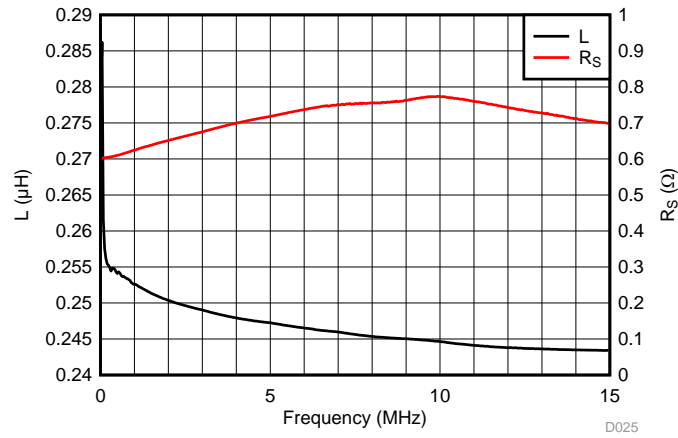


Figure 26. Coil N: L, R_s vs. Frequency

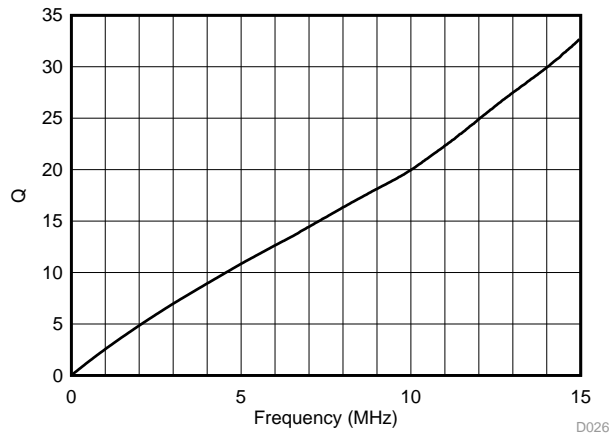


Figure 27. Coil N: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil O: 8mm, 11 turns, 4mil trace, 4mil spacing, 4 layers

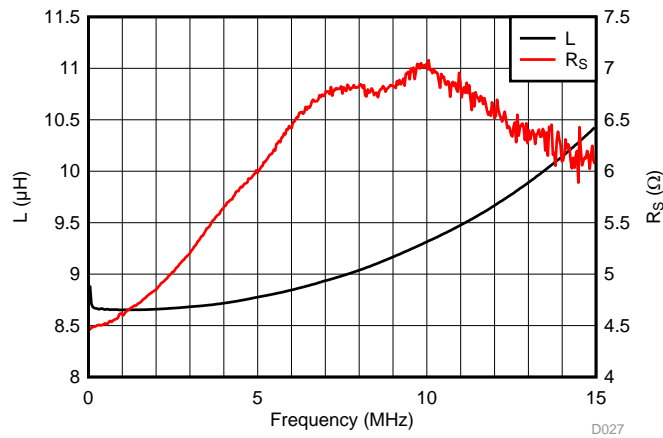


Figure 28. Coil O: L, R_s vs. Frequency

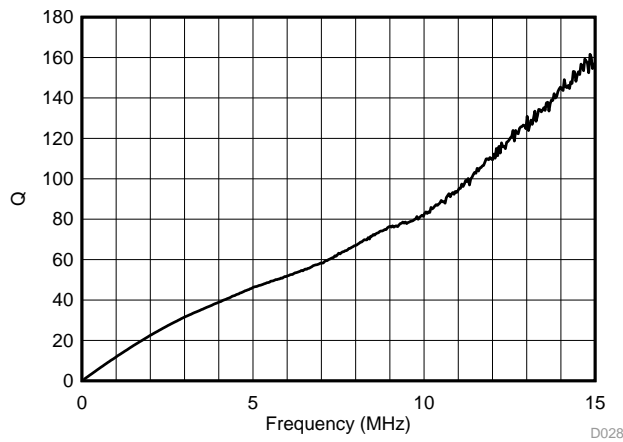


Figure 29. Coil O: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil P: 5mm, 9 turns, 4mil trace, 4mil spacing, 4 layers

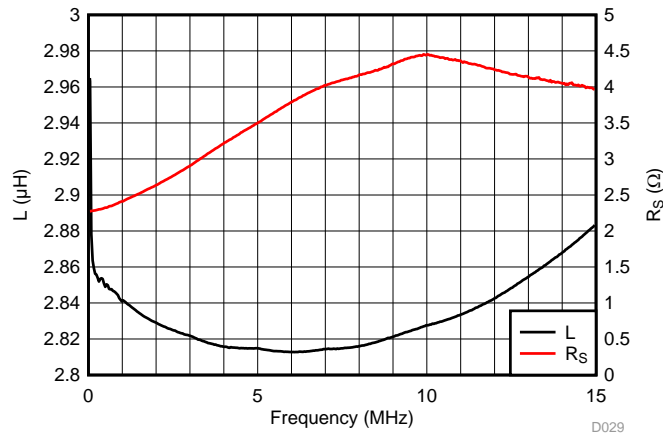


Figure 30. Coil P: L, R_s vs. Frequency

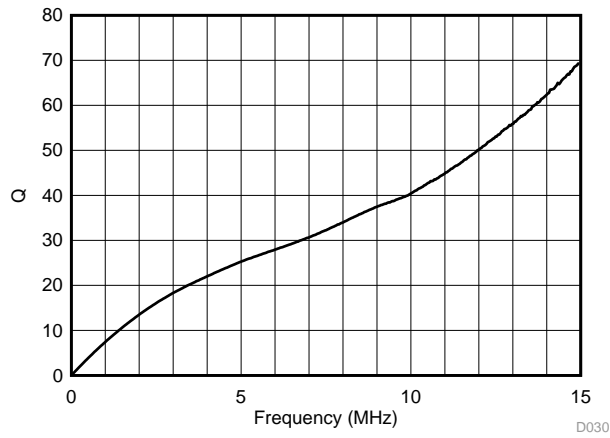


Figure 31. Coil P: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil Q: 6mm, 9 turns, 4mil trace, 4mil spacing, 4 layers

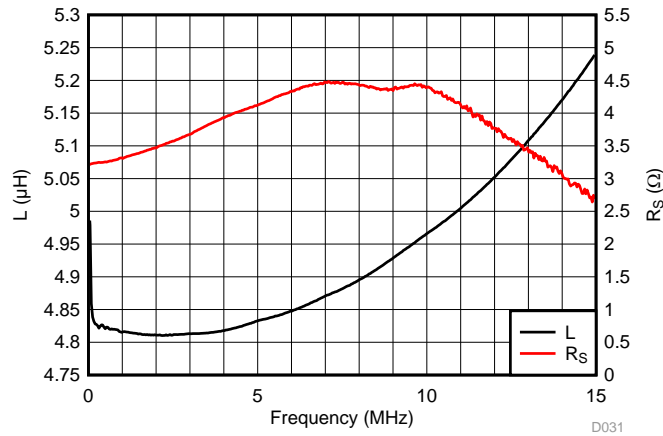


Figure 32. Coil Q: L, R_s vs. Frequency

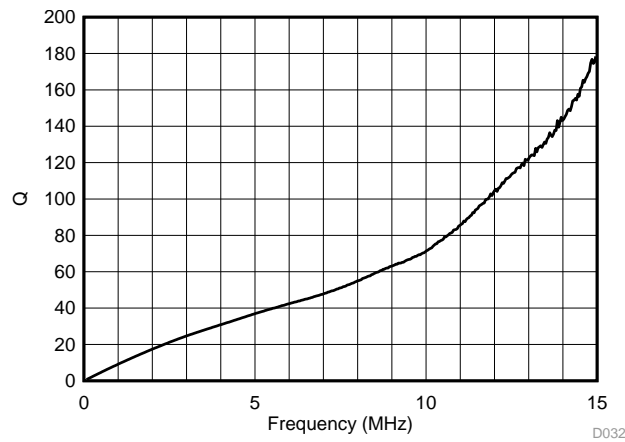


Figure 33. Coil Q: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil R: 4mm, 6 turns, 4mil trace, 4mil spacing, 4 layers

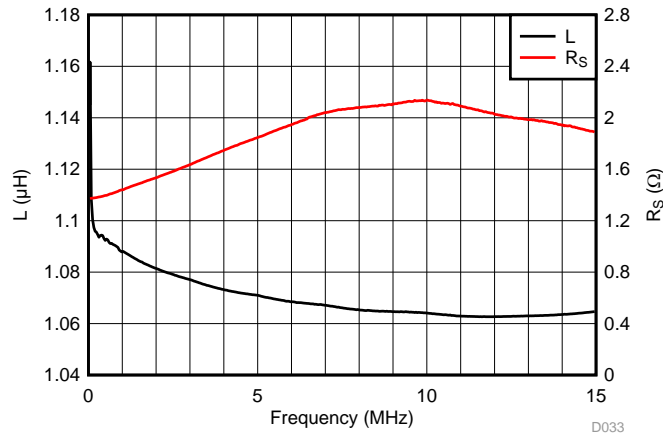


Figure 34. Coil R: L, R_s vs. Frequency

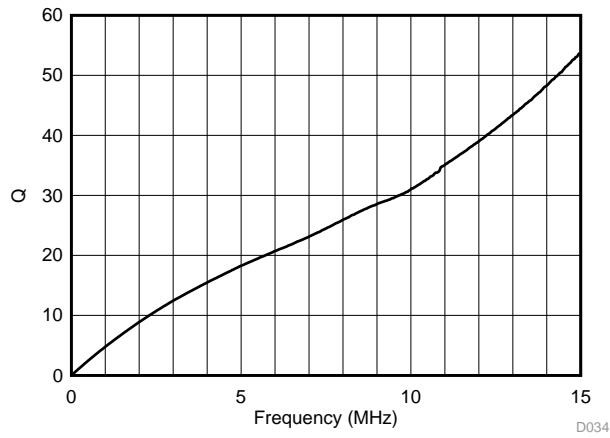


Figure 35. Coil R: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

Coil S: 10mm, 16 turns, 4mil trace, 4mil spacing, 2 layers

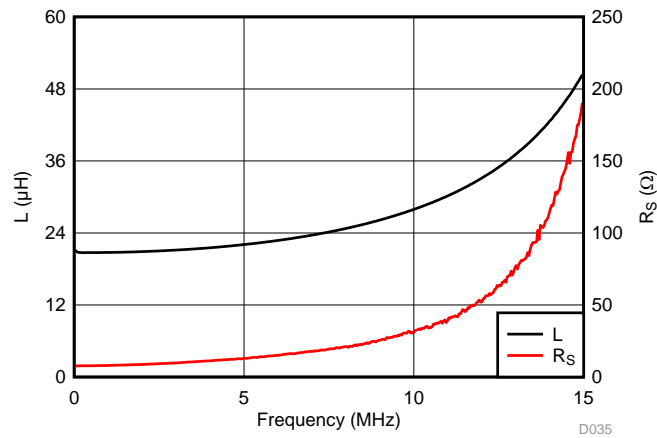


Figure 36. Coil S: L, R_s vs. Frequency

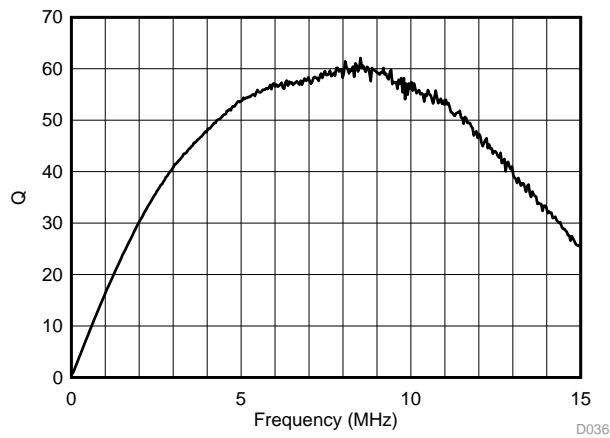


Figure 37. Coil S: Q vs. Frequency

Self-resonant frequency (SRF): greater than 15MHz

4 PCB Layout

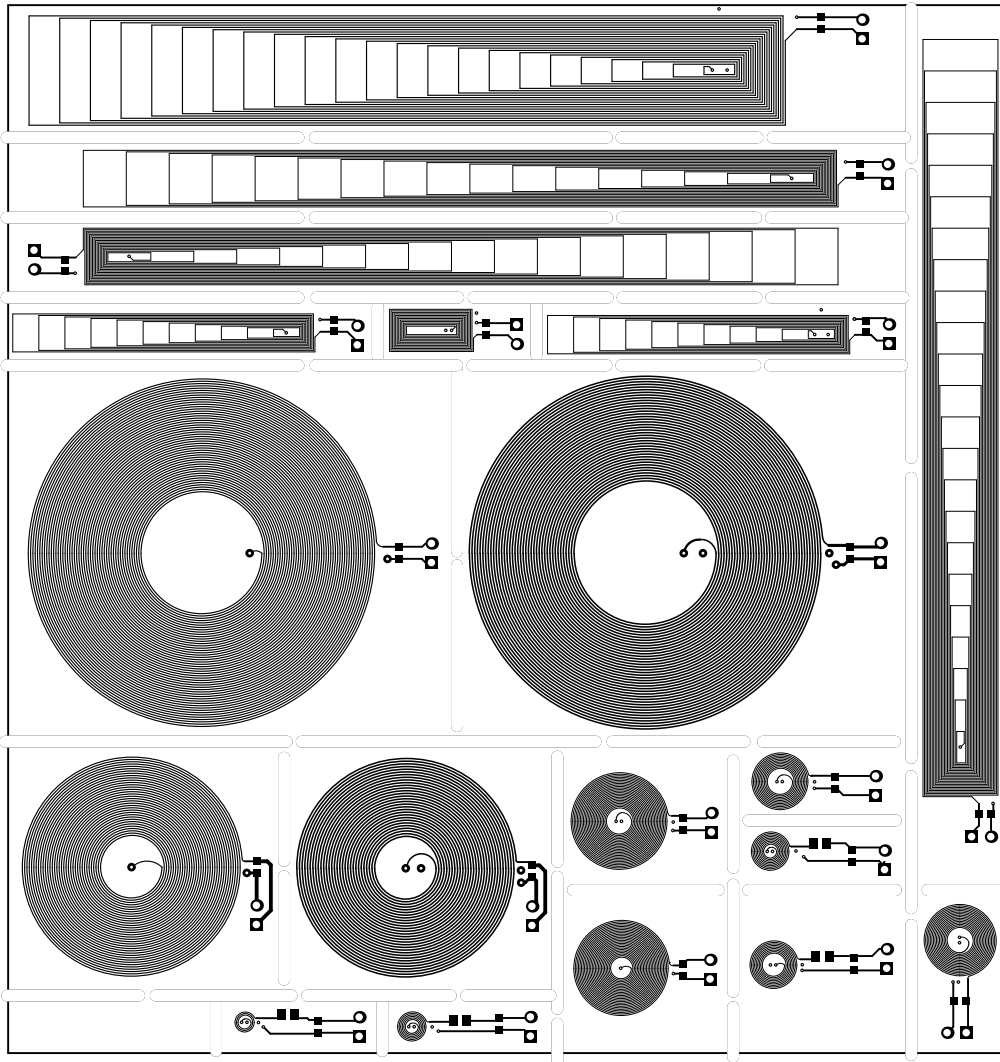


Figure 38. Reference Coils PCB Layout - Top Layer

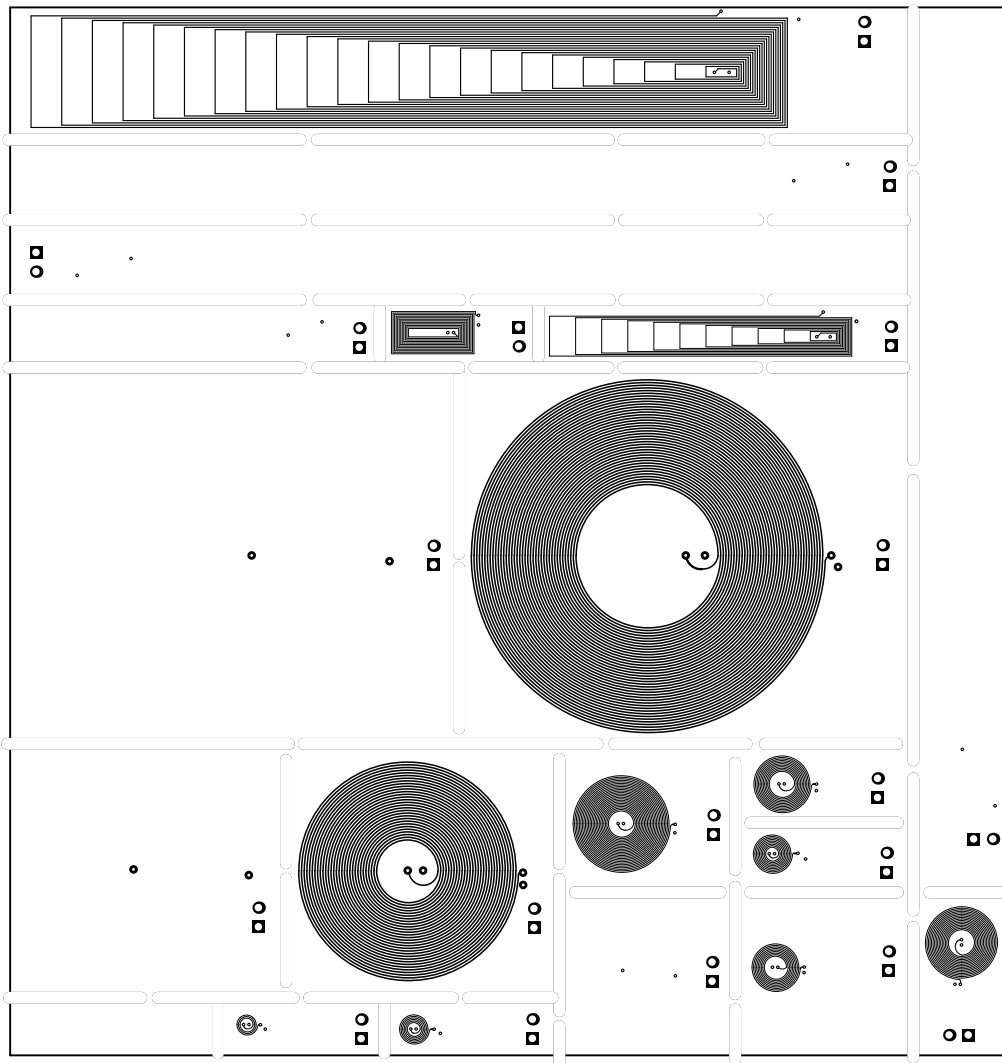


Figure 39. Reference Coils PCB Layout - Mid-Layer 1

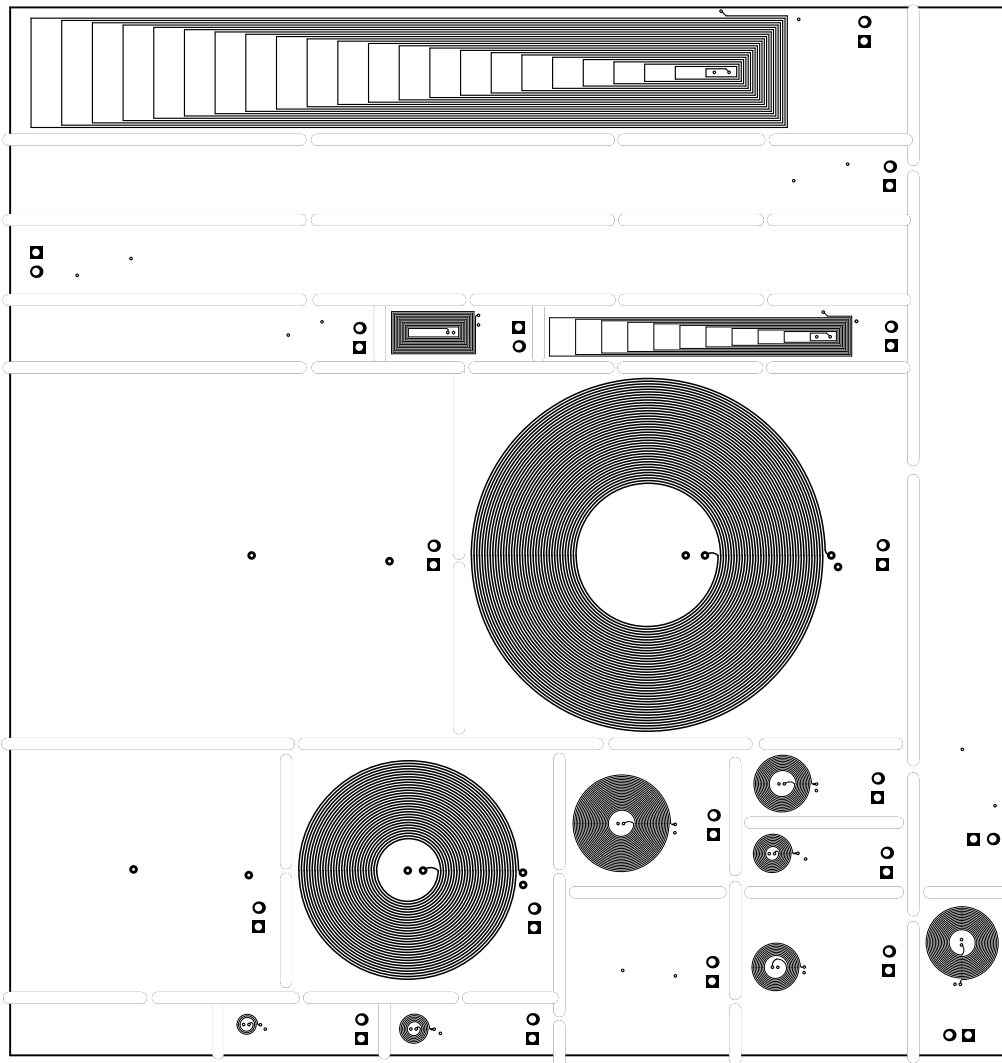


Figure 40. Reference Coils PCB Layout - Mid-Layer 2

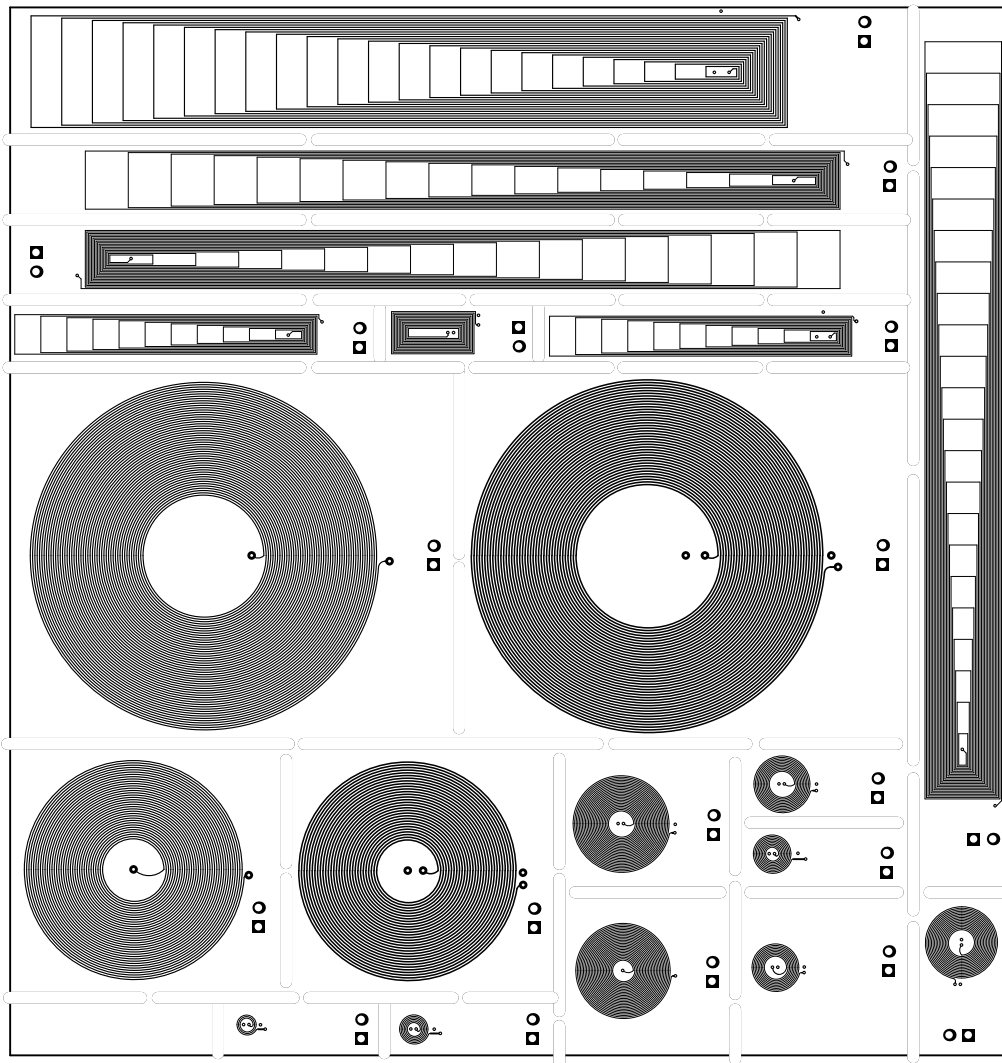


Figure 41. Reference Coils PCB Layout - Bottom Layer

STANDARD TERMS AND CONDITIONS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, or documentation (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms and conditions set forth herein. Acceptance of the EVM is expressly subject to the following terms and conditions.
 - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductor products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms and conditions that accompany such Software
 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
 - 2.1 These terms and conditions do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
 - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for any defects that are caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI. Moreover, TI shall not be liable for any defects that result from User's design, specifications or instructions for such EVMs. Testing and other quality control techniques are used to the extent TI deems necessary or as mandated by government requirements. TI does not test all parameters of each EVM.
 - 2.3 If any EVM fails to conform to the warranty set forth above, TI's sole liability shall be at its option to repair or replace such EVM, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
 - 3.1 *United States*
 - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required by Radio Law of Japan to follow the instructions below with respect to EVMs:

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

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4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

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